Hewlett Packard Enterprise

Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
HPE ProLiant ML30 Gen10

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2012/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		5
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

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Item Description	Notes	Quantity of items included in product
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T10 T15
Philips screw driver	Cross No.1
Sharp Nose Pliers	
Scissors	

3.0 Product Disassembly Process

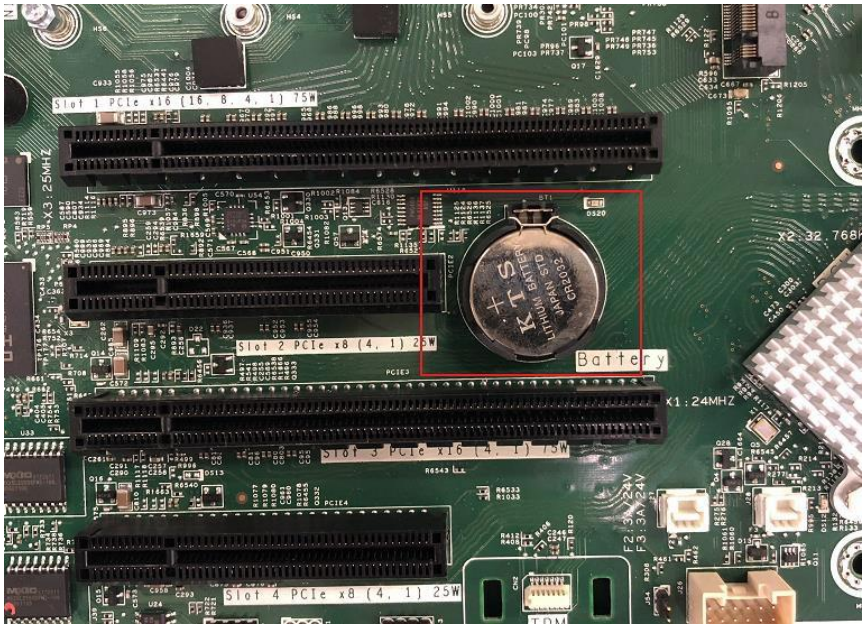
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. System Board Battery - Remove the side panel and remove the battery from the system board.
2. Capacitance which is inserted by operator–First, let tin touch the two pin of the capacitance ,second, soldering tin the points with Soldering Station which set the temperature to 330 ± 10oC for L/F model , if non-L/F model, set the temperature to 300 ± 10oC, remove capacitance from PCB after tin completely melting, and then put it into Recycled Box(Remark: if capacitance which is disassembled is GND ,Set the Soldering Station(Gao Zhou)temperature to 385oC).
3. Capacitors in 350W power supply => Remove the power supply from the system. With a Philips screw driver remove the screws securing the top cover and loosen the screws securing the PCA. Then use Sharp Nose Pliers to remove the daughter card, and electrolyte-capacitor.
4. Capacitors in 500W PSU => Push latch and remove PSU from the system. With a Philips screw driver remove the screws securing the cover and take the PCA out. Then use Sharp Nose Pliers to remove the daughter card, and electrolyte-capacitor. Then use Sharp Nose Pliers to remove the daughter card, and electrolyte-capacitor.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

System battery location

System battery location – BT1



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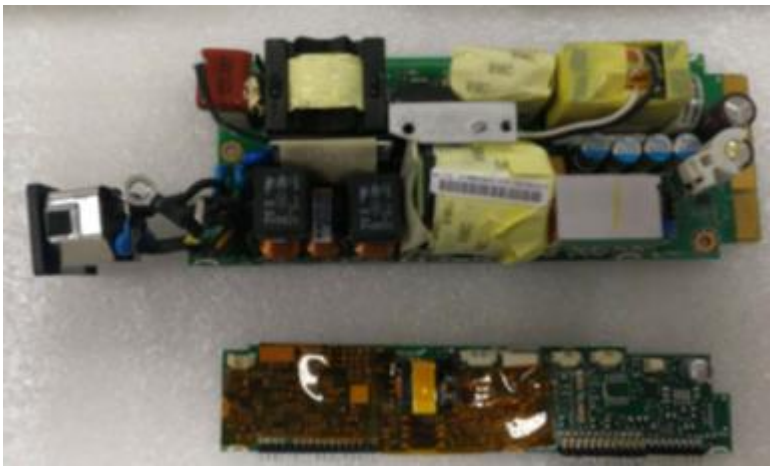
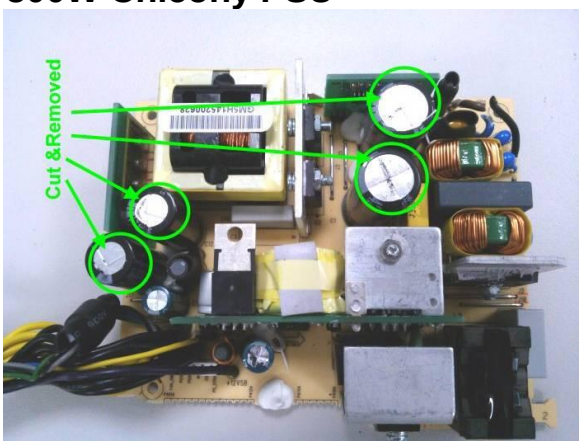
500W Delta PSU

500W Lite-on PSU



500W Chicony PSU



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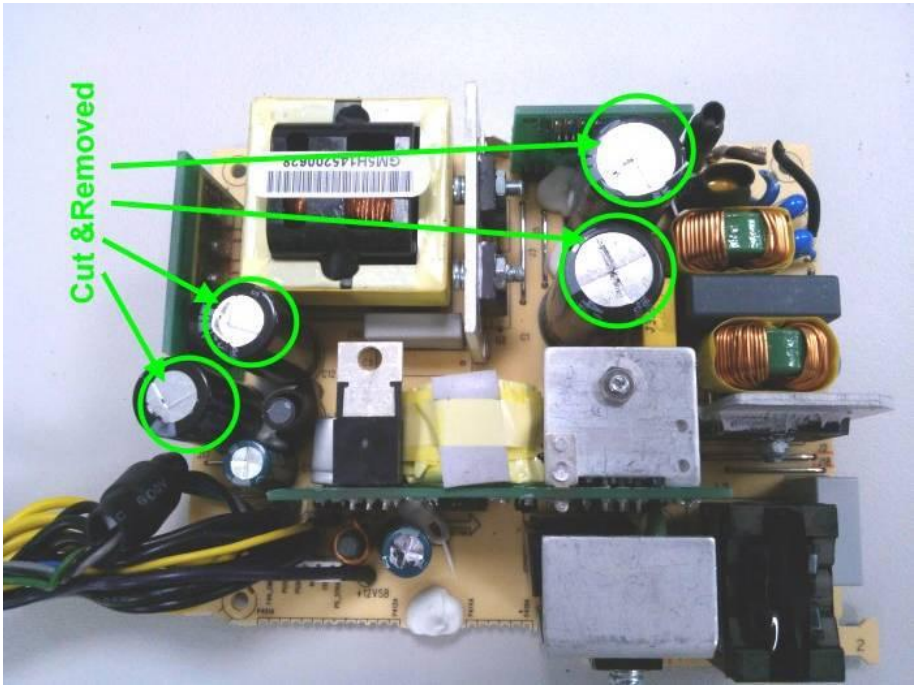
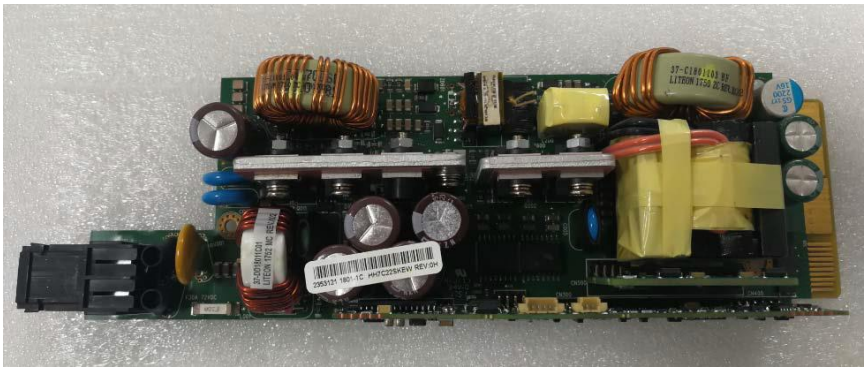
290W Chicony PSU



800W Lite-On PSU



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